

Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junctions
- Fast switching for high efficiency
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC



SMA (DO-214AC)

Mechanical Date

- **Case:** JEDEC DO-214AC molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per JESD22-B102
- **Polarity:** Laser band denotes cathode end

Major Ratings and Characteristics

$I_{F(AV)}$	2.0 A
V_{RRM}	50 V to 1000 V
I_{FSM}	50 A
t_{rr}	150nS, 250nS, 500nS
V_F	1.3 V
$T_j \text{ max.}$	150 °C

Maximum Ratings & Thermal Characteristics

($T_A = 25\text{ °C}$ unless otherwise noted)

Items	Symbol	RS2A	RS2B	RS2D	RS2G	RS2J	RS2K	RS2M	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	2.0							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	50							A
Thermal resistance from junction to lead ⁽¹⁾	$R_{\theta JL}$	35							°C/W
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							°C

Note 1: Mounted on P.C.B. with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.

Electrical Characteristics ($T_A = 25\text{ °C}$ unless otherwise noted)

Items	Test conditions	Symbol	RS2A~RS2G	RS2J	RS2K~RS2M	UNIT
Instantaneous forward voltage	$I_F = 2.0\text{ A}^{(2)}$	V_F	1.3			V
Reverse current	$V_R = V_{DC}$	I_R	$T_J = 25\text{ °C}$			5
			$T_J = 125\text{ °C}$			50
Reverse recovery time	$I_F = 0.5\text{ A}, I_R = 1.0\text{ A}, I_{rr} = 0.25\text{ A}$	t_{rr}	150	250	500	nS
Typical junction capacitance	4.0 V, 1MHz	C_J	15		11	pF

Note 2: Pulse test: 300µs pulse width, 1% duty cycle.

Characteristic Curves ($T_A=25\text{ }^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

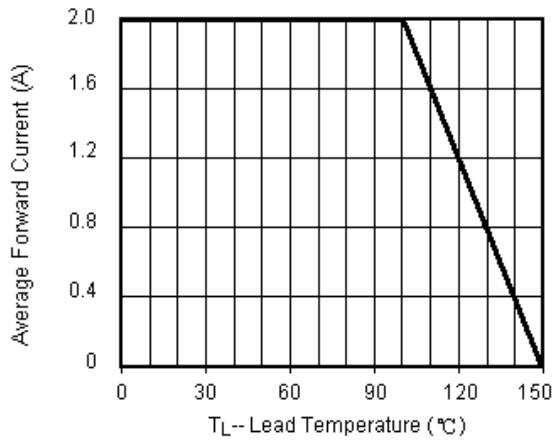


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

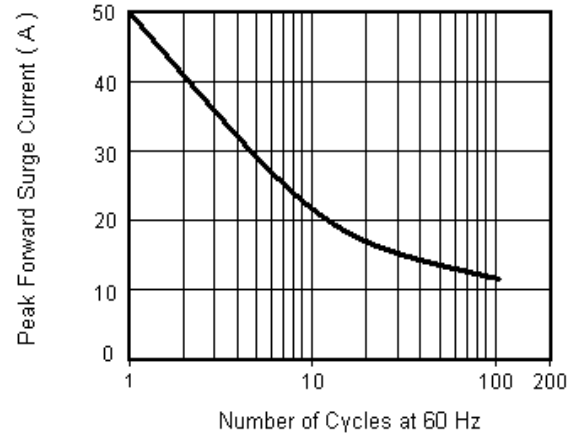


Fig.3 Typical Instantaneous Forward Characteristics

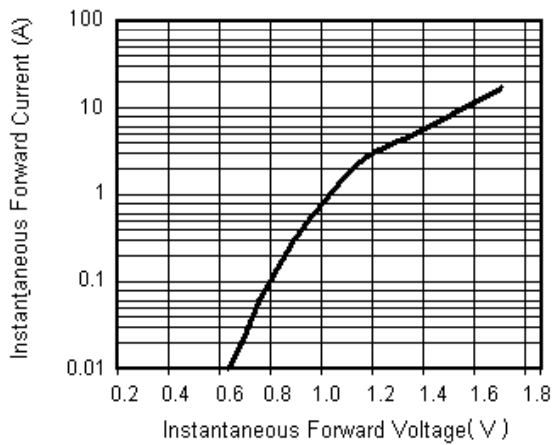
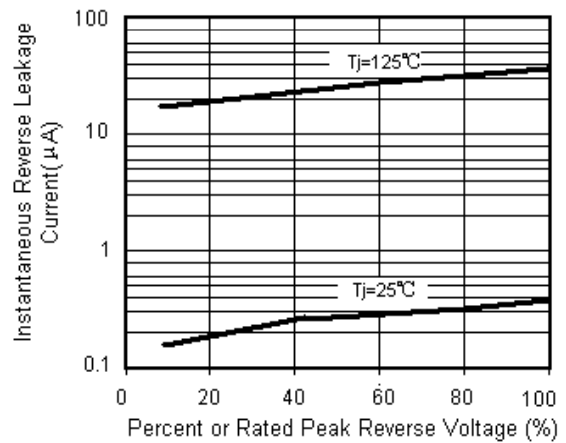
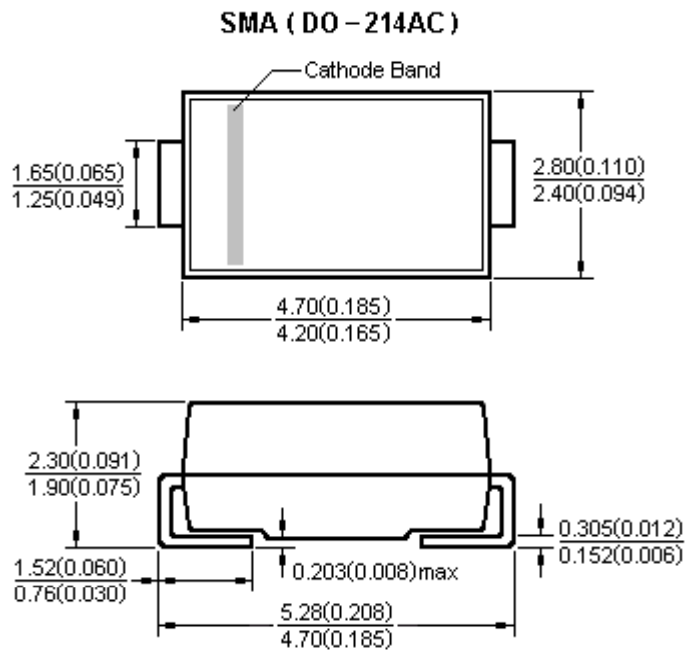


Fig.4 Typical Reverse Leakage Characteristics



Package Outline



Dimensions in millimeters and (inches)

Notice

- Product is intended for use in general electronics applications.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage. or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.

$I_{F(AV)}$: We recommend that the worst case current be no greater than 80% .

T_J : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a T_J of below 125°C.

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